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Part Number: **0736561000**
Status: **Active**
Overview: HDM® Backplane Connector System
Description: HDM Board-to-Board Backplane Power Module, Vertical, SMC, Power Receptacle, 3 Circuits, Gold (Au) 0.76µm

Documents:

3D Model	Application Specification AS-73656-1998-001 (PDF)
Drawing (PDF)	Packaging Specification PK-70873-0819 (PDF)
Product Specification PS-73670-9999 (PDF)	RoHS Certificate of Compliance (PDF)

Agency Certification

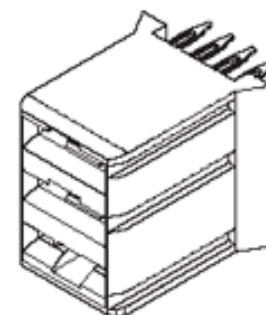
CSA	LR19980
UL	E29179

General

Product Family	Backplane Connectors
Series	<u>73656</u>
Application	Backplane
Comments	Midplane Power Module
Component Type	Power Header
Overview	<u>HDM® Backplane Connector System</u>
Product Name	HDM®
UPC	800755024791

Physical

Circuits (Loaded)	3
Circuits (maximum)	3
Color - Resin	Black
Durability (mating cycles max)	250
First Mate / Last Break	No
Flammability	94V-0
Guide to Mating Part	No
Keying to Mating Part	None
Material - Metal	Beryllium Copper
Material - Plating Mating	Gold
Material - Plating Termination	Gold
Material - Resin	High Temperature Thermoplastic
Net Weight	1.605/g
Number of Columns	1
Number of Pairs	Open Pin Field
Number of Rows	3
Orientation	Vertical
PC Tail Length	3.50mm
PCB Locator	No
PCB Retention	Yes
PCB Thickness - Recommended	2.50mm
Packaging Type	Tube
Pitch - Mating Interface	2.00mm
Pitch - Termination Interface	2.00mm
Plating min - Mating	0.762µm
Plating min - Termination	0.051µm
Polarized to PCB	Yes
Stackable	No
Surface Mount Compatible (SMC)	No
Temperature Range - Operating	-55°C to +105°C
Termination Interface: Style	Through Hole - Compliant Pin



Series image - Reference only

EU ELV

Not Relevant

EU RoHS

Compliant

REACH SVHC

Not Contained Per - ED/30/2017 (7 July 2017)

Halogen-Free

Status

Low-Halogen

Need more information on product environmental compliance?

Email productcompliance@molex.com
Please visit the [Contact Us](#) section for any non-product compliance questions.

China ROHS	Green Image
ELV	Not Relevant
RoHS Phthalates	Not Contained

Search Parts in this Series

73656 Series

Mates With

73651 HDM Board-to-Board Daughterboard Power Module

Electrical

Current - Maximum per Contact	15.0A
Data Rate	1.0 Gbps
Shielded	No
Voltage - Maximum	500V AC

Solder Process Data

Lead-freeProcess Capability	N/A
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Material Info**Reference - Drawing Numbers**

Application Specification	AS-73656-1998-001
Packaging Specification	PK-70873-0819
Product Specification	PS-73670-9999
Sales Drawing	SDA-73656-*00*

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